

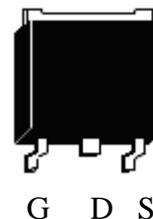
## P-Channel Logic Level Enhancement Mode Power MOSFET

### Features:

- Low Gate Charge
- Simple Drive Requirement
- Pb-free lead plating & halogen-free package

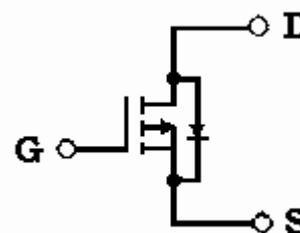
### Outline

TO-252(DPAK)



### Equivalent Circuit

KWB90P06J3



G : Gate D : Drain S : Source

$BV_{DSS}$	-60V
$I_D$	-12A
$R_{DS(on)}@V_{GS}=-10V, I_D=-10A$	70 m $\Omega$ (typ)
$R_{DS(on)}@V_{GS}=-5V, I_D=-8A$	90 m $\Omega$ (typ)

### Ordering Information

Device	Package	Shipping
KWB90P06J3	TO-252 (Pb-free lead plating & Halogen-free package)	2500 pcs / Tape & Reel

**Absolute Maximum Ratings** ( $T_C=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current @ $T_C=25^{\circ}\text{C}$	$I_D$	-12	A
Continuous Drain Current @ $T_C=100^{\circ}\text{C}$	$I_D$	-8.5	
Pulsed Drain Current *1	$I_{DM}$	-40	
Avalanche Current	$I_{AS}$	-10	
Avalanche Energy @ $L=0.1\text{mH}$ , $I_D=-10\text{A}$ , $R_G=25\Omega$	$E_{AS}$	5	mJ
Repetitive Avalanche Energy @ $L=0.05\text{mH}$ *2	$E_{AR}$	2	
Total Power Dissipation @ $T_C=25^{\circ}\text{C}$	$P_d$	33	W
Total Power Dissipation @ $T_C=100^{\circ}\text{C}$		10	
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	-55~+175	$^{\circ}\text{C}$

Note : \*1. Pulse width limited by maximum junction temperature  
 \*2. Duty cycle  $\leq 1\%$

**Thermal Data**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	4.5	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-ambient, max	$R_{th,j-a}$	110	$^{\circ}\text{C}/\text{W}$

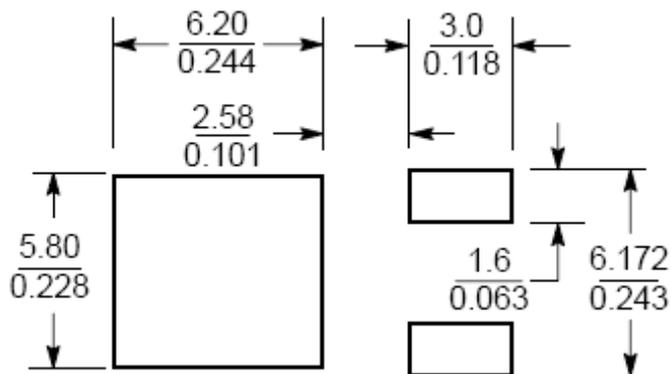
**Characteristics** ( $T_C=25^{\circ}\text{C}$ , unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
$BV_{DSS}$	-60	-	-	V	$V_{GS}=0, I_D=-250\mu\text{A}$
$V_{GS(th)}$	-1	-1.7	-2.5		$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$
$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20, V_{DS}=0$
$I_{DSS}$	-	-	-1	$\mu\text{A}$	$V_{DS}=-32\text{V}, V_{GS}=0$
	-	-	-25		$V_{DS}=-30\text{V}, V_{GS}=0, T_J=125^{\circ}\text{C}$
$I_{D(ON)}$ *1	-12	-	-	A	$V_{DS}=-5\text{V}, V_{GS}=-4.5\text{V}$
$R_{DS(ON)}$ *1	-	70	90	$\text{m}\Omega$	$V_{GS}=-10\text{V}, I_D=-10\text{A}$
	-	90	140	$\text{m}\Omega$	$V_{GS}=-5\text{V}, I_D=-8\text{A}$
$G_{FS}$ *1	-	13	-	S	$V_{DS}=-5\text{V}, I_D=-10\text{A}$
<b>Dynamic</b>					
$Q_g$ *1, 2	-	16	-	nC	$V_{DS}=-30\text{V}, I_D=-12\text{A}, V_{GS}=-10\text{V}$
$Q_{gs}$ *1, 2	-	3.7	-		
$Q_{gd}$ *1, 2	-	5	-		
$t_{d(ON)}$ *1, 2	-	7	-	ns	$V_{DS}=-10\text{V}, I_D=-1\text{A}, V_{GS}=-10\text{V}, R_G=6\Omega$
$t_r$ *1, 2	-	10	-		
$t_{d(OFF)}$ *1, 2	-	30	-		
$t_f$ *1, 2	-	7	-		

Ciss	-	1005	-	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =-25V, f=1MHz
Coss	-	51	-		
Crss	-	41	-		
Rg	-	6.8	-	Ω	V <sub>GS</sub> =15mV, V <sub>DS</sub> =0, f=1MHz
<b>Source-Drain Diode</b>					
I <sub>S</sub> *1	-	-	-12	A	
I <sub>SM</sub> *3	-	-	-40		
V <sub>SD</sub> *1	-	-0.92	-1.3	V	I <sub>F</sub> =-10A, V <sub>GS</sub> =0V
trr	-	12	-	ns	I <sub>F</sub> =-5A, dI <sub>F</sub> /dt=100A/μs
Qrr	-	9	-	nC	

Note : \*1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%  
 \*2.Independent of operating temperature  
 \*3.Pulse width limited by maximum junction temperature.

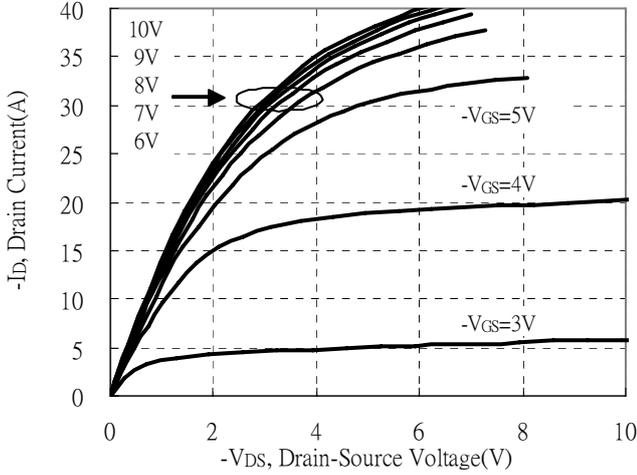
**Recommended soldering footprint**



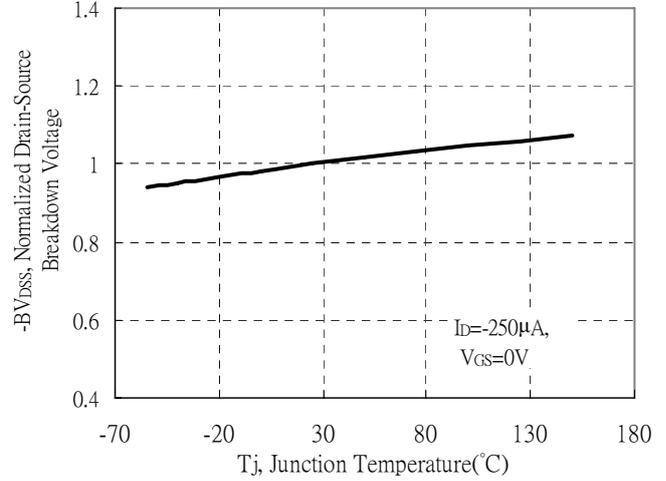
Unit (  $\frac{\text{mm}}{\text{inch}}$  )

**Typical Characteristics**

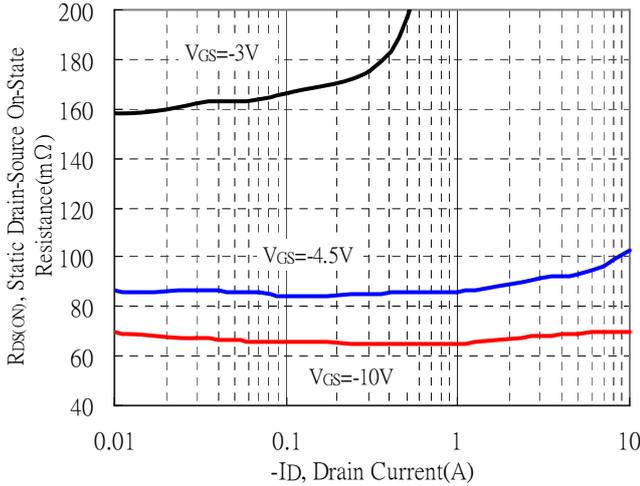
Typical Output Characteristics



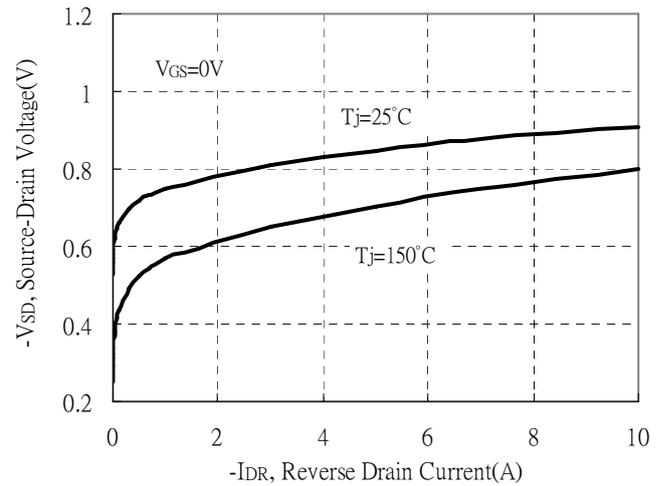
Brekdown Voltage vs Ambient Temperature



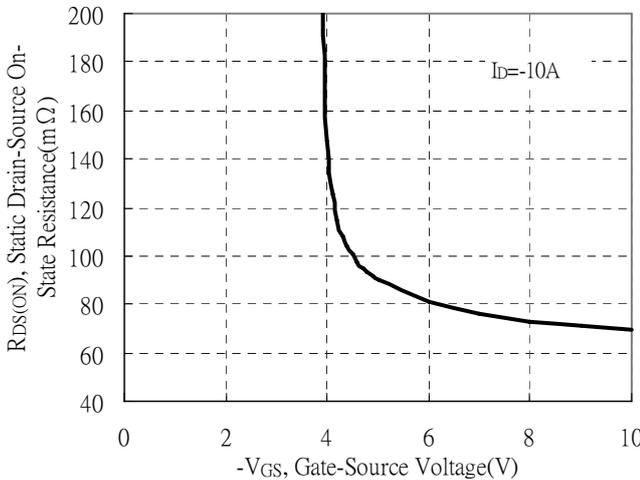
Static Drain-Source On-State resistance vs Drain Current



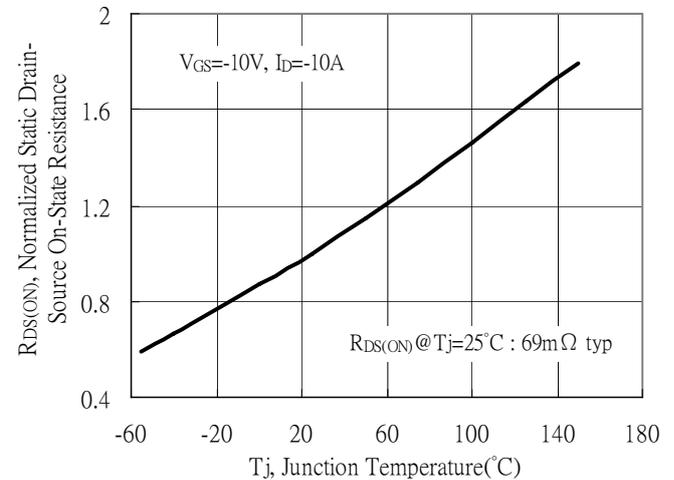
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

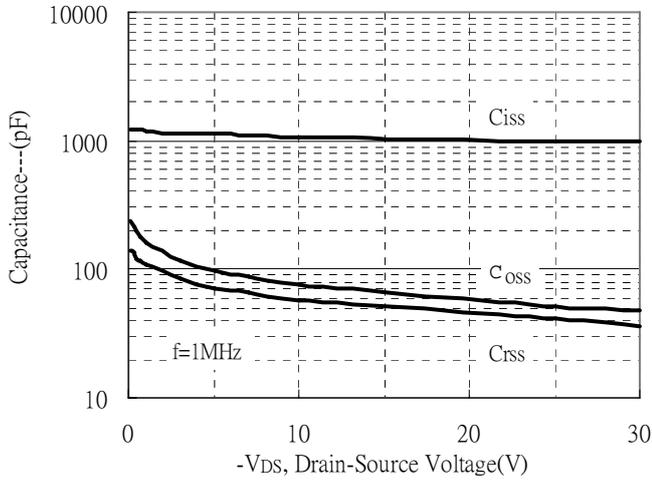


Drain-Source On-State Resistance vs Junction Temperature

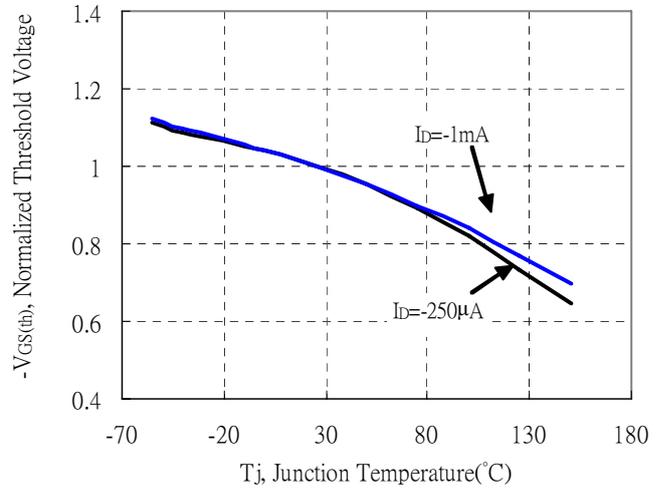


**Typical Characteristics(Cont.)**

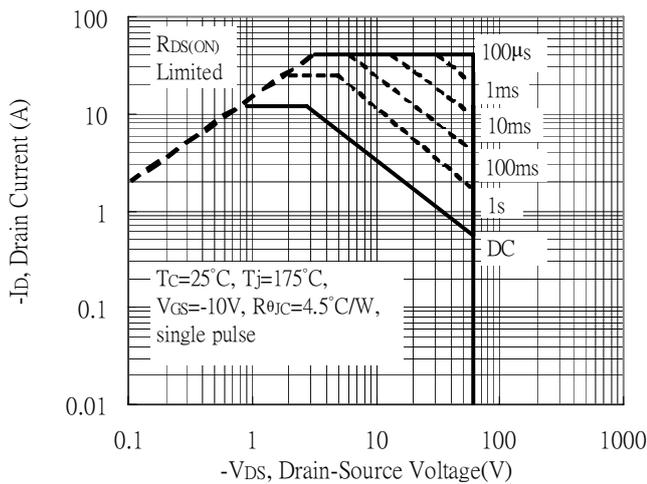
Capacitance vs Drain-to-Source Voltage



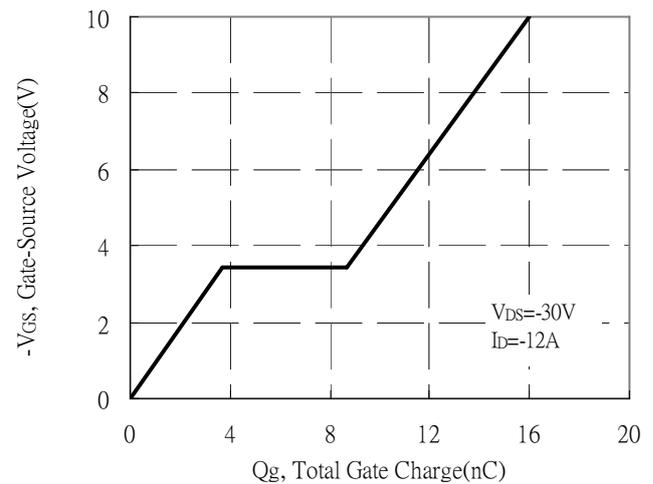
Threshold Voltage vs Junction Temperature



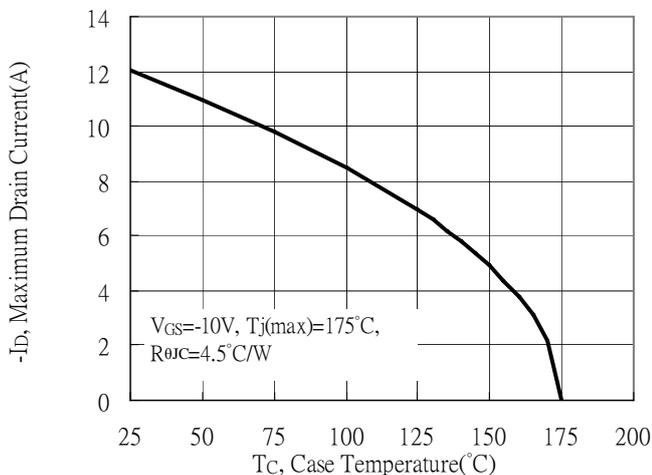
Maximum Safe Operating Area



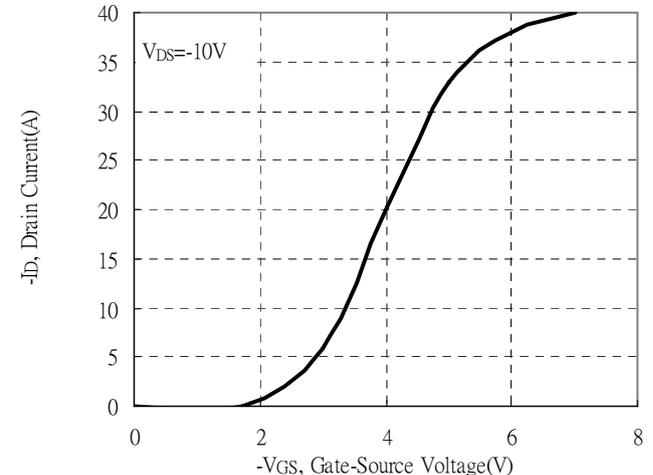
Gate Charge Characteristics



Maximum Drain Current vs Case Temperature

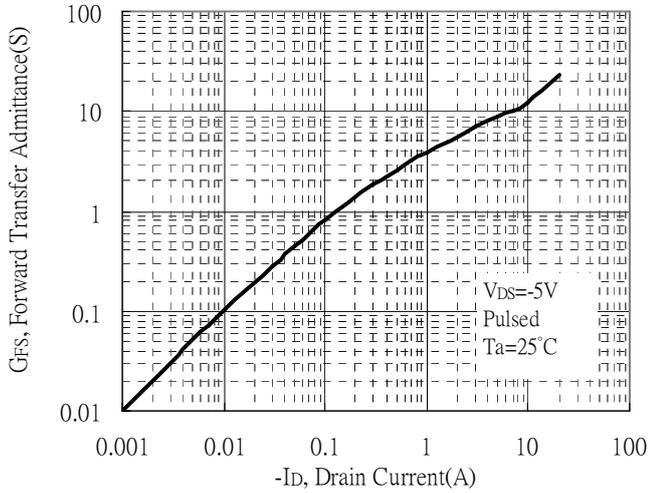


Typical Transfer Characteristics

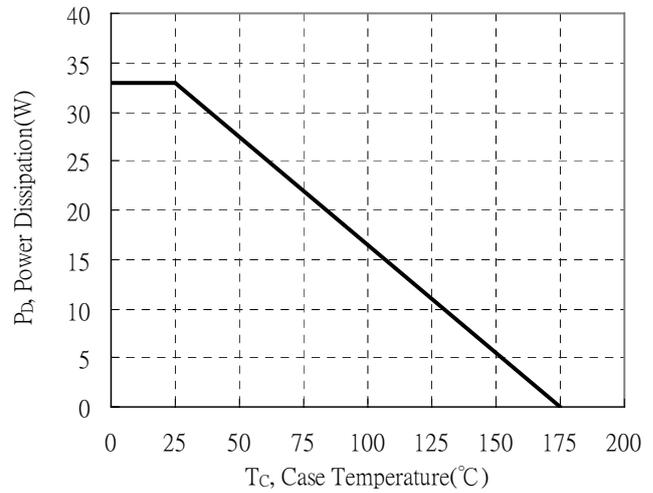


**Typical Characteristics(Cont.)**

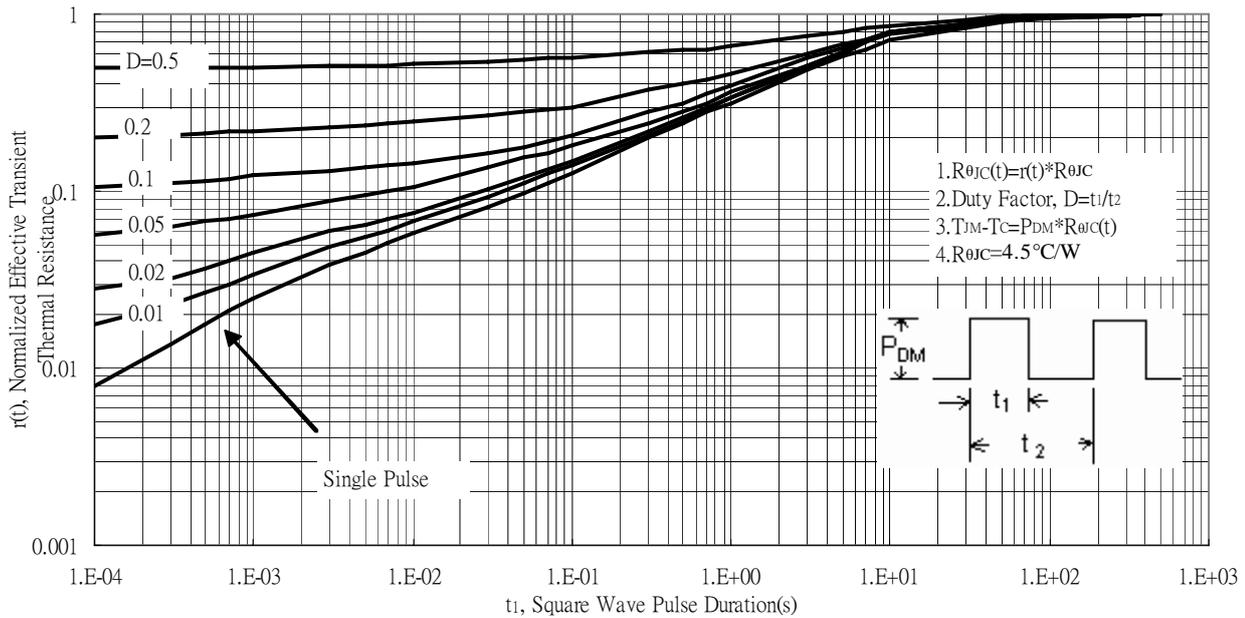
Forward Transfer Admittance vs Drain Current



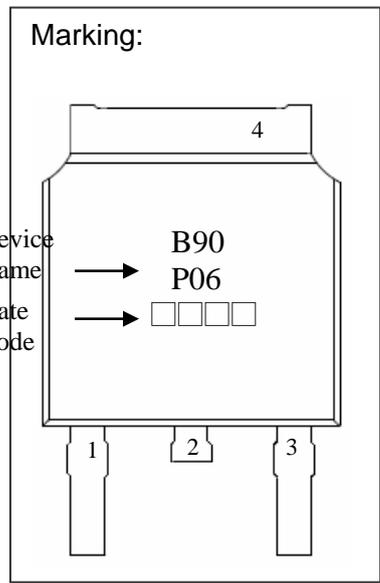
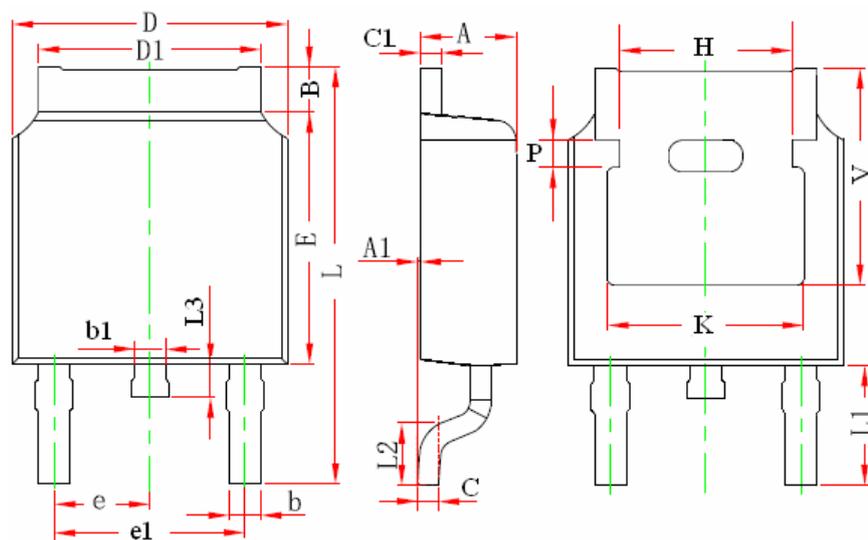
Power Derating Curve



Transient Thermal Response Curves



**TO-252 Dimension**



3-Lead TO-252 Plastic Surface Mount  
 Package Code: J3

Style: Pin 1.Gate 2.Drain 3.Source  
 4.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	e	0.086	0.094	2.186	2.386
A1	0.000	0.005	0.000	0.127	e1	0.172	0.188	4.372	4.772
B	0.039	0.048	0.990	1.210	H	0.163	REF	4.140	REF
b	0.026	0.034	0.660	0.860	K	0.190	REF	4.830	REF
b1	0.026	0.034	0.660	0.860	L	0.386	0.409	9.800	10.400
C	0.018	0.023	0.460	0.580	L1	0.114	REF	2.900	REF
C1	0.018	0.023	0.460	0.580	L2	0.055	0.067	1.400	1.700
D	0.256	0.264	6.500	6.700	L3	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	P	0.026	REF	0.650	REF
E	0.236	0.244	6.000	6.200	V	0.211	REF	5.350	REF